Technical Data Sheet

VieTape TIM4105

THERMALLY CONDUCTIVE ELECTRICALLY INSULATING PAD

DESCRIPTION

High - performance thermally conductive insulating pad reinforced with polyimide film, which has excellent cut through resistance and low thermal resistance. It can be used in electronic and electrical applications that require both thermal conductivity and electrical insulation.

APPLICATIONS

Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, ...

TYPICAL PERFORMANCE PROPERTIES

PROPERTIES	VALUE	METHOD
Appearance	Gray	Visual
Composition	Silicone pad + Polyimide Film	
Thickness	0.15mm	ASTM D374
Density	2.5 g/cm ³	ASTM D792
Working Temperature	-60 to 180°C	-
Hardness	85 shore A	ASTM D2240
Tear Strength	25KN/m	ASTM D412
	ELECTRICAL PROPERTIES	
Breakdown Voltage	>6.0 kV/mm	ASTM D149
Volume Resistivity	10 ¹⁴ Ohm-cm	ASTM D257
	THERMAL PROPERTIES	
Thermal conductivity	1.3 W/m.K	ASTM D5470
Thermal resistance (°C*in²/W)	0.28 @50psi	ASTM D5470
Flammability	Meet UL94-V0	

SHELF LIFE AND STORAGE

12 months from date of manufacture when stored at 10 - 30° C and 40 - 50° C relative humidity. Avoid extrusion and exposure to the sun.

The data contained in this bulletin is provided only as a guide for evaluation/consideration. These material characteristics are typical properties that are based on a limited number of samples tested in the laboratory. We cannot assume responsibility for results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any product or method. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide.

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